

In the Specification:

The paragraph beginning on page 1, line 19 has been amended as follows:

--The storage density of these kinds of disk drives is greatly increasing, as well as is the density of tracks on the magnetic disk. It is especially possible to increase the density by using a MR (GMR, TMR) head as the magnetic head. Therefore, a high precision device is also desired for processing of the head signal.--

The paragraph beginning on page 1, line 25 has been amended as follows:

--In a magnetic disk device, the magnetic head is supported by a suspension. The suspension is attached to the carriage arm of a VCM actuator. The suspension has springiness and functions such that the magnetic head ~~follow~~follows the surface of the magnetic disk. The magnetic head performs input/output of an analog signal, so it is equipped with a head IC for processing the analog signal. The head IC comprises a preamp for amplifying the read signal of the magnetic head, and a writing amp for supplying writing current to the magnetic head.--

The paragraph beginning on page 2, line 15 has been amended as follows:

--In addition, when the lead wire is long, the rising time and falling time of the pulse signal (writing pulse) both becomes long, so there is a problem in that it becomes difficult to transfer data at high speed. Therefore, it is proposed to place the head IC chip on the suspension in order to shorten the distance between the magnetic head and the head IC.--

The paragraph beginning on page 3, line 1 has been amended as follows:

--However, with the prior method, the head and head IC of the HGA unit are checked together so when one is determined to be faulty that ~~fully-entire~~ HGA ~~becomes~~ is considered faulty. Therefore, there is a problem that yield decreases and it is difficult to keep costs down.--

The paragraph beginning on page 10, line 18 has been amended as follows:

--The suspension base 27 is formed from stainless steel or the like. There is a thin film pattern that is formed from the insulation layer on the base 27. This thin film pattern comprises: a first connection terminal 21 for electrically connecting with the magnetic head 4; a second connection terminal 22 for connecting to external circuits; third and fourth connection terminals 23, 24 for electrically connecting to the head IC that processes the electrical signal from the magnetic head; a first conductive path 28 that connects the first connection terminal ~~22~~21 and the third connection terminal; a second conductive path 26 that connects the second connection terminal 22 and the fourth connection terminal 24; and a measurement terminal 25, that is located between the second terminal 22 and fourth connection terminal 24 on the second conductive path 26, and is for measuring the head IC 20.—

The paragraph beginning on page 12, line 18 has been amended as follows:

--Moreover, in order to check the head IC 20 on the suspension 9, it is necessary for the measurement probes 32 to come in contact with the terminals. It is possible to check the head IC 20 by ~~bring~~bringing the probes 32 ~~in~~into contact with the first terminal 21 and second terminal 25 instead of the third and fourth terminals on the head IC. However, the second connection terminal ~~25~~22 for external connection is located in a position that is easy for external connection (to the side of the suspension 9 in Fig. 5) and it is not easy to place a probe 32 on it. Therefore, in this invention, a measurement terminal 25 is located between the second and fourth connection terminals 22, 24. This makes contact with the probe 32 easy and makes it possible to quickly check the head IC.--

The paragraph beginning on page 13 line 5 has been amended as follows:

--Furthermore, in the head suspension of this invention, the measurement terminal 25 and the first connection terminal are on the same plane of the suspension 9. In this way it is even easier for making contact with the pair of probes 32, which makes it possible to check the head IC 20 even more quickly.--